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Ref #	Hits	Search Query	DBS	Default Operator	Plurals	Time Stamp
L1	111699	(resist or photoresist or mask or photomask).clm.	US-PGPUB; USPAT	OR	ON	2006/02/15 17:29
L2	27630	bevel\$.clm.	US-PGPUB; USPAT	OR	ON	2006/02/15 17:29
.L3	275400	(bond\$ or laminat\$).clm.	US-PGPUB; USPAT	OR	ON	2006/02/15 17:30
L4	283586	(wafer\$ or semiconduct\$ or chip). clm.	US-PGPUB; USPAT	OR	ON	2006/02/15 17:30
L5	5	1 and 2 and 3 and 4	US-PGPUB; USPAT	OR	ON ·	2006/02/15 17:33
L6	16140	(hp or hewlett).as.	US-PGPUB; USPAT	OR	ON	2006/02/15 17:33
L7	495	morrow-p\$.in. or list-r\$.in. or chan-m\$.in.	US-PGPUB; USPAT	OR	ON	2006/02/15 17:34
L8	1	1 and 2 and 3 and 7	US-PGPUB; USPAT	OR	ON	2006/02/15 17:34
L9	0	1 and 2 and 3 and 6	US-PGPUB; USPAT	OR	ON	2006/02/15 17:34
L10	12	1 and 3 and 4 and (6 or 7)	US-PGPUB; USPAT	OR	ON	2006/02/15 17:34
L11	11	10 not (8 or 5)	US-PGPUB; USPAT	OR	ON	2006/02/15 17:35
L12	4	11 and circuit.clm.	US-PGPUB; USPAT	OR	ON	2006/02/15 17:36
L13	7	11 not 12	US-PGPUB; USPAT	OR	ON	2006/02/15 17:36

USP7, WPID JP DBs **Plurals** Ref Default Hits Search Query Time Stamp Operator # L1 2345 device and handle and (wafer or JPO; OR ON 2006/02/15 20:26 DERWENT semiconduct\$ or chip) OR ON L2 etch\$ or patern\$ or remov\$ JPO: 2006/02/15 20:33 1736352 DERWENT L3 OR ON 2006/02/15 20:26 392 1 and 2 JPO; **DERWENT** OR ON L4 356997 (resist or photoresist or mask or JPO: 2006/02/15 20:33 photomask) DERWENT ON L5 44 3 and 4 JPO: OR 2006/02/15 20:29 DERWENT OR ON L6 5 and bevel\$ JPO: 2006/02/15 20:34 0 DERWENT ON L7 OR 2006/02/15 20:33 49628 device with wafer JPO; DERWENT OR ON JPO; L8 1409 handle with wafer 2006/02/15 20:33 **DERWENT** 7 and 8 and 2 OR ON L9 92 JPO: 2006/02/15 20:29 DERWENT **OR** ON 12 4 and 9 2006/02/15 20:29 L10 JPO; **DERWENT** ON L11 71481 device with wafer US-PGPUB; OR 2006/02/15 20:33 USPAT L12 3555 handle with wafer **US-PGPUB**; OR ON 2006/02/15 20:33 **USPAT** ON L13 2611625 etch\$ or patern\$ or remov\$ **US-PGPUB**: OR 2006/02/15 20:33 **USPAT** L14 519756 (resist or photoresist or mask or **US-PGPUB**; OR ON 2006/02/15 20:33 photomask) **USPAT** US-PGPUB; OR ON L15 111746 bevel\$ 2006/02/15 20:34 USPAT ON L16 67 11 same 12 same 13 same 14 **US-PGPUB**; OR 2006/02/15 20:34 **USPAT** L17 US-PGPUB; ON 2006/02/15 20:35 2 16 same 15 OR USPAT **US-PGPUB**; ON L18 65 16 not 17 OR 2006/02/15 20:37 **USPAT** 0 16 same (overhang\$ or undercut\$ US-PGPUB; ON. L19 OR' 2006/02/15 20:36 or "over hang\$" or "under cut\$") **USPAT** L20 18 and bevel\$ **US-PGPUB**; ON 0 OR 2006/02/15 20:36 **USPAT** ON L21 device same bevel\$ same handle **US-PGPUB**; OR 2006/02/15 20:36 same 14 same 13 **USPAT** L22 ON 166250 13 with 14 **US-PGPUB**; OR 2006/02/15 20:38 USPAT

L23	58	16 same 22	US-PGPUB; USPAT	OR	ON	2006/02/15 20:38
L24	56	18 and 23	US-PGPUB; USPAT	OR	ON	2006/02/15 20:38
L25	20740	22 with device	US-PGPUB; USPAT	OR	ON	2006/02/15 20:39
L26	21	16 same 25	US-PGPUB; USPAT	OR	ON	2006/02/15 20:39
L27	21	24 and 26	US-PGPUB; USPAT	OR	ON	2006/02/15 20:41
L28	35	24 not 27	US-PGPUB; USPAT	OR	ON	2006/02/15 20:41